

PIC16C710/711

PIC16C71 → PIC16C710/711 Data Sheet Errata

The PIC16C710/711 parts you have received conform functionally to the Device Data Sheet (DS40032**B**), except for the anomalies described below.

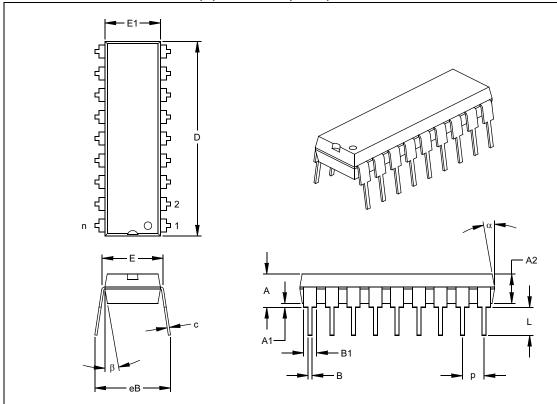
None.

Clarifications/Corrections to the Data Sheet:

1. Module: Packaging

The package information contained in the data sheet is incorrect. Please refer to the following tables for correct package data.

18-Lead Plastic Dual In-line (P) - 300 mil (PDIP)



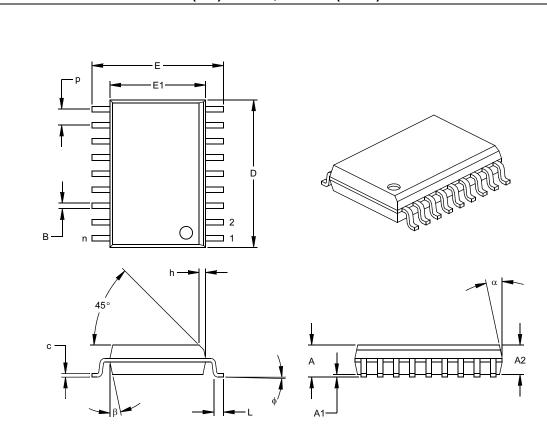
	Units	INCHES*			MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		18			18		
Pitch	р		.100			2.54		
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32	
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68	
Base to Seating Plane	A1	.015			0.38			
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26	
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60	
Overall Length	D	.890	.898	.905	22.61	22.80	22.99	
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43	
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38	
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78	
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56	
Overall Row Spacing §	eВ	.310	.370	.430	7.87	9.40	10.92	
Mold Draft Angle Top	α	5	10	15	5	10	15	
Mold Draft Angle Bottom	β	5	10	15	5	10	15	

^{*} Controlling Parameter § Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001
Decided No. C04-007

18-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)



	Units	Units INCHES*			MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		18			18		
Pitch	р		.050			1.27		
Overall Height	Α	.093	.099	.104	2.36	2.50	2.64	
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39	
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30	
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67	
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59	
Overall Length	D	.446	.454	.462	11.33	11.53	11.73	
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74	
Foot Length	L	.016	.033	.050	0.41	0.84	1.27	
Foot Angle	ф	0	4	8	0	4	8	
Lead Thickness	С	.009	.011	.012	0.23	0.27	0.30	
Lead Width	В	.014	.017	.020	0.36	0.42	0.51	
Mold Draft Angle Top	α	0	12	15	0	12	15	
Mold Draft Angle Bottom	β	0	12	15	0	12	15	

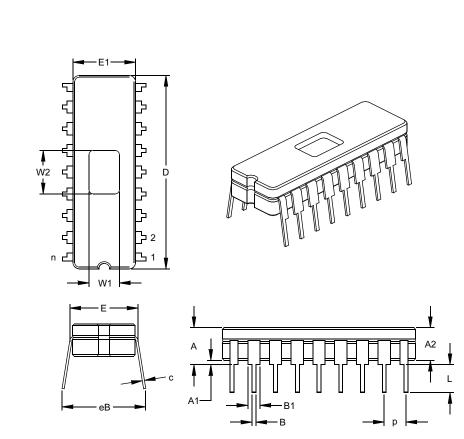
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

^{*} Controlling Parameter § Significant Characteristic

18-Lead Ceramic Dual In-line with Window (JW) - 300 mil (CERDIP)



	Units	INCHES*			MILLIMETERS			
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		18			18		
Pitch	р		.100			2.54		
Top to Seating Plane	Α	.170	.183	.195	4.32	4.64	4.95	
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19	
Standoff	A1	.015	.023	.030	0.38	0.57	0.76	
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26	
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49	
Overall Length	D	.880	.900	.920	22.35	22.86	23.37	
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81	
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30	
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52	
Lower Lead Width	В	.016	.019	.021	0.41	0.47	0.53	
Overall Row Spacing §	eВ	.345	.385	.425	8.76	9.78	10.80	
Window Width	W1	.130	.140	.150	3.30	3.56	3.81	
Window Length	W2	.190	.200	.210	4.83	5.08	5.33	

^{*} Controlling Parameter § Significant Characteristic JEDEC Equivalent: MO-036 Drawing No. C04-010

APPENDIX A: REVISION HISTORY

Rev. A Document (3/2003)

Under Clarifications/Corrections to the Data Sheet, Item 1, Packaging: correct package data was added.

PIC16C710/711

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
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